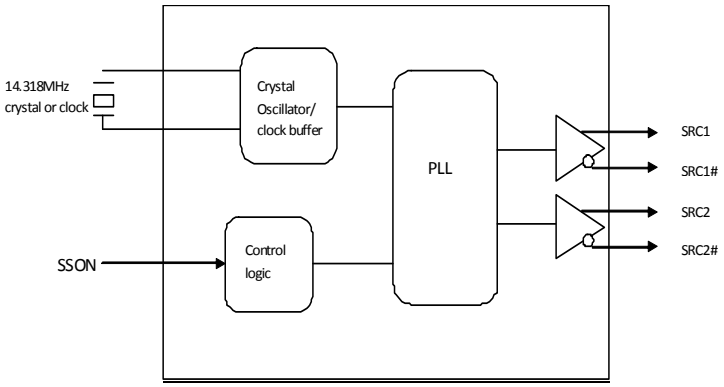
PCI Express Gen 2 & Gen 3 Clock Generator

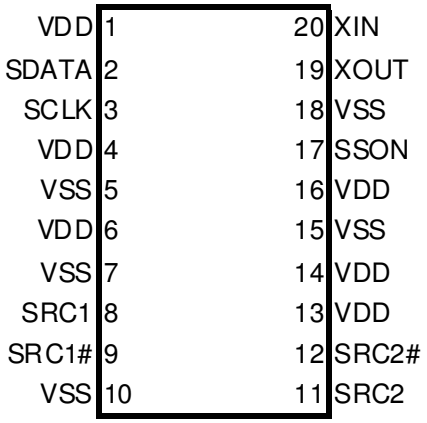
Features

- Low power PCI Express Gen 2 & Gen 3 clock generator
- Two100-MHz differential SRC clocks
- Low power push-pull output buffers (no 50ohm to ground needed)
- Integrated 33ohm series termination resistors
- Low jitter (<50pS)
- SSON input for enabling spread spectrum clock
- I^2C support with readback capabilities
- Triangular Spread Spectrum profile for maximum electromagnetic interference (EMI) reduction
- Input frequency of 14.318MHz
- Industrial Temperature -40°C to 85°C
- 3.3V power supply
- 20-pin TSSOP package

Block Diagram



Pin Configuration



2200 Laurelwood Road, Santa Clara, CA 95054 Tel:(408) 855-0555 Fax:(408) 855-0550 www.SpectraLinear.com

Pin Definitions

Pin No.	Name	Type	Description
1	VDD	PWR	3.3V Power supply
2	SDATA	I/O	SMBus compatible SDATA.
3	SCLK	I	SMBus compatible SCLOCK.
4	VDD	PWR	3.3V power supply
5	VSS	GND	Ground
6	VDD	PWR	3.3V power supply
7	VSS	GND	Ground
8	SRC1	O, DIF	100 MHz Differential serial reference clocks.
9	SRC1#	O, DIF	100 MHz Differential serial reference clocks.
10	VSS	GND	Ground
11	SRC2	O, DIF	100 MHz Differential serial reference clocks.
12	SRC2#	O, DIF	100 MHz Differential serial reference clocks.
13	VDD	PWR	3.3V power supply
14	VDD	PWR	3.3V power supply
15	VSS	GND	Ground
16	VDD	PWR	3.3V power supply
17	SSON	I	3.3V LVTTL input for enabling spread spectrum clock 0 = Disable, 1 = Enable (-0.5% SS) External 10K ohm pull-up or pull-down resistor required
18	VSS	GND	Ground
19	XOUT	O, SE	14.318 MHz Crystal output.
20	XIN	I	14.318 MHz Crystal input.

Serial Data Interface

To enhance the flexibility and function of the clock synthesizer, a two-signal serial interface is provided. Through the Serial Data Interface, various device functions, such as individual clock output buffers are individually enabled or disabled. The registers associated with the Serial Data Interface initialize to their default setting at power-up. The use of this interface is optional. Clock device register changes are normally made at system initialization, if any are required. The interface cannot be used during system operation for power management functions.

Data Protocol

The clock driver serial protocol accepts byte write, byte read, block write, and block read operations from the controller. For block write/read operation, Access the bytes in sequential order from lowest to highest (most significant bit first) with the ability to stop after any complete byte is transferred. For byte write and byte read operations, the system controller can access individually indexed bytes. The offset of the indexed byte is encoded in the command code described in *Table 1*.

The block write and block read protocol is outlined in *Table 2* while *Table 3* outlines byte write and byte read protocol. The slave receiver address is 11010010 (D2h)

Table 1. Command Code Definition

Bit	Description
7	0 = Block read or block write operation, 1 = Byte read or byte write operation
(6:0)	Byte offset for byte read or byte write operation. For block read or block write operations, these bits should be '0000000'

Table 2. Block Read and Block Write Protocol

Block Write Protocol		Block Read Protocol	
Bit	**Description**	**Bit**	**Description**
1	Start	1	Start
8:2	Slave address–7 bits	8:2	Slave address–7 bits
9	Write	9	Write
10	Acknowledge from slave	10	Acknowledge from slave
18:11	Command Code–8 bits	18:11	Command Code–8 bits
19	Acknowledge from slave	19	Acknowledge from slave
27:20	Byte Count–8 bits	20	Repeat start
28	Acknowledge from slave	27:21	Slave address–7 bits
36:29	Data byte 1–8 bits	28	Read = 1
37	Acknowledge from slave	29	Acknowledge from slave
45:38	Data byte 2–8 bits	37:30	Byte Count from slave–8 bits
46	Acknowledge from slave	38	Acknowledge
....	Data Byte /Slave Acknowledges	46:39	Data byte 1 from slave–8 bits
....	Data Byte N–8 bits	47	Acknowledge
....	Acknowledge from slave	55:48	Data byte 2 from slave–8 bits
....	Stop	56	Acknowledge
		....	Data bytes from slave / Acknowledge
		....	Data Byte N from slave–8 bits
		....	NOT Acknowledge
		....	Stop

Table 3. Byte Read and Byte Write Protocol

Byte Write Protocol		Byte Read Protocol	
Bit	**Description**	**Bit**	**Description**
1	Start	1	Start
8:2	Slave address–7 bits	8:2	Slave address–7 bits
9	Write	9	Write
10	Acknowledge from slave	10	Acknowledge from slave
18:11	Command Code–8 bits	18:11	Command Code–8 bits
19	Acknowledge from slave	19	Acknowledge from slave
27:20	Data byte–8 bits	20	Repeated start
28	Acknowledge from slave	27:21	Slave address–7 bits
29	Stop	28	Read
		29	Acknowledge from slave
		37:30	Data from slave–8 bits
		38	NOT Acknowledge
		39	Stop

Control Registers

Byte 0: Control Register 0

Bit	@Pup	Name	Description
7	HW	RESERVED	RESERVED
6	0	RESERVED	RESERVED
5	1	RESERVED	RESERVED
4	0	RESERVED	RESERVED
3	0	RESERVED	RESERVED
2	0	RESERVED	RESERVED
1	0	RESERVED	RESERVED
0	1	RESERVED	RESERVED

Byte 1: Control Register 1

Bit	@Pup	Name	Description
7	1	RESERVED	RESERVED
6	0	PLL1_SS_DC	Select for down or center SS 0 = Down spread, 1 = Center spread
5	0	RESERVED	RESERVED
4	0	RESERVED	RESERVED
3	0	RESERVED	RESERVED
2	1	RESERVED	RESERVED
1	0	RESERVED	RESERVED
0	1	RESERVED	RESERVED

Byte 2: Control Register 2

Bit	@Pup	Name	Description
7	1	RESERVED	RESERVED
6	1	RESERVED	RESERVED
5	1	RESERVED	RESERVED
4	1	RESERVED	RESERVED
3	1	RESERVED	RESERVED
2	1	RESERVED	RESERVED
1	1	RESERVED	RESERVED
0	1	RESERVED	RESERVED

Byte 3: Control Register 3

Bit	@Pup	Name	Description
7	1	RESERVED	RESERVED
6	1	RESERVED	RESERVED
5	1	RESERVED	RESERVED
4	1	RESERVED	RESERVED
3	1	RESERVED	RESERVED
2	1	RESERVED	RESERVED
1	1	RESERVED	RESERVED
0	1	RESERVED	RESERVED

Byte 4: Control Register 4

Bit	@Pup	Name	Description
7	1	RESERVED	RESERVED
6	1	SRC1_OE	Output enable for SRC1 0 = Output Disabled, 1 = Output Enabled
5	1	SRC2_OE	Output enable for SRC2 0 = Output Disabled, 1 = Output Enabled
4	1	RESERVED	RESERVED
3	1	RESERVED	RESERVED
2	1	RESERVED	RESERVED
1	1	PLL1_SS_EN	Enable PLL1s spread modulation, 0 = Spread Disabled, 1 = Spread Enabled
0	1	RESERVED	RESERVED

Byte 5: Control Register 5

Bit	@Pup	Name	Description
7	0	RESERVED	RESERVED
6	0	RESERVED	RESERVED
5	0	RESERVED	RESERVED
4	0	RESERVED	RESERVED
3	0	RESERVED	RESERVED
2	0	RESERVED	RESERVED
1	0	RESERVED	RESERVED
0	0	RESERVED	RESERVED

Byte 6: Control Register 6

Bit	@Pup	Name	Description
7	0	RESERVED	RESERVED
6	0	RESERVED	RESERVED
5	0	RESERVED	RESERVED
4	0	RESERVED	RESERVED
3	0	RESERVED	RESERVED
2	0	RESERVED	RESERVED
1	0	RESERVED	RESERVED
0	0	RESERVED	RESERVED

Byte 7: Vendor ID

Bit	@Pup	Name	Description
7	0	Rev Code Bit 3	Revision Code Bit 3
6	0	Rev Code Bit 2	Revision Code Bit 2
5	1	Rev Code Bit 1	Revision Code Bit 1
4	1	Rev Code Bit 0	Revision Code Bit 0
3	1	Vendor ID bit 3	Vendor ID Bit 3
2	0	Vendor ID bit 2	Vendor ID Bit 2
1	0	Vendor ID bit 1	Vendor ID Bit 1
0	0	Vendor ID bit 0	Vendor ID Bit 0

Byte 8: Control Register 8

Bit	@Pup	Name	Description
7	1	Device_ID3	RESERVED
6	0	Device_ID2	RESERVED
5	0	Device_ID1	RESERVED
4	0	Device_ID0	RESERVED
3	0	RESERVED	RESERVED
2	0	RESERVED	RESERVED
1	1	RESERVED	RESERVED
0	1	RESERVED	RESERVED

Byte 9: Control Register 9

Bit	@Pup	Name	Description
7	0	RESERVED	RESERVED
6	0	RESERVED	RESERVED
5	1	RESERVED	RESERVED
4	0	TEST _MODE_SEL	Test mode select either REF/N or tri-state 0 = All outputs tri-state, 1 = All output REF/N
3	0	TEST_MODE_ENTRY	Allows entry into test mode 0 = Normal Operation, 1 = Enter test mode(s)
2	1	12C_VOUT<2>	I2C_VOUT[2:0] 000 = 0.30V 001 = 0.40V 010 = 0.50V 011 = 060V 100 = 0.70V 101 = 0.80V (default) 110 = 0.90V 111 = 1.00V
1	0	12C_VOUT<1>	
0	1	12C_VOUT<0>	

Byte 10: Control Register 10

Bit	@Pup	Name	Description
7	0	RESERVED	RESERVED
6	0	RESERVED	RESERVED
5	0	RESERVED	RESERVED
4	0	RESERVED	RESERVED
3	0	RESERVED	RESERVED
2	0	RESERVED	RESERVED
1	1	RESERVED	RESERVED
0	1	RESERVED	RESERVED

Byte 11: Control Register 11

Bit	@Pup	Name	Description
7	0	RESERVED	RESERVED
6	0	RESERVED	RESERVED
5	0	RESERVED	RESERVED
4	0	RESERVED	RESERVED
3	0	RESERVED	RESERVED

Byte 11: Control Register 11 (continued)

2	1	RESERVED	RESERVED
1	1	PCI-E_GEN2	PCI-E_Gen2 Compliant 0 = non Gen2, 1= Gen2 Compliant
0	1	RESERVED	RESERVED

Byte 12: Byte Count

Bit	@Pup	Name	Description
7	0	BC7	Byte count register for block read operation. The default value for Byte count is 14. In order to read more than 14 bytes, the system BIOS needs to change this register to the number of bytes to be read.
6	0	BC6	
5	0	BC5	
4	0	BC4	
3	1	BC3	
2	1	BC2	
1	1	BC1	
0	1	BC0	

Table 4. Crystal Recommendations

Frequency (Fund)	Cut	Loading	Load Cap	Drive (max.)	Shunt Cap (max.)	Motional (max.)	Tolerance (max.)	Stability (max.)	Aging (max.)
14.31818 MHz	AT	Parallel	20 pF	0.1 mW	5 pF	0.016 pF	35 ppm	30 ppm	5 ppm

The SL28SRC02 requires a Parallel Resonance Crystal. Substituting a series resonance crystal causes the SL28SRC02 to operate at the wrong frequency and violates the ppm specification. For most applications there is a 300-ppm frequency shift between series and parallel crystals due to incorrect loading

Crystal Loading

Crystal loading plays a critical role in achieving low ppm performance. To realize low ppm performance, use the total capacitance the crystal sees to calculate the appropriate capacitive loading (CL).

Figure 1 shows a typical crystal configuration using the two trim capacitors. It is important that the trim capacitors are in series with the crystal. It is not true that load capacitors are in parallel with the crystal and are approximately equal to the load capacitance of the crystal.

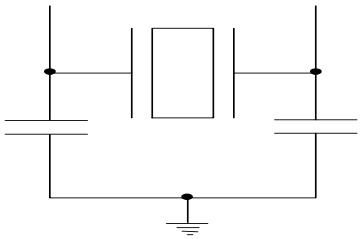


Figure 1. Crystal Capacitive Clarification

Calculating Load Capacitors

In addition to the standard external trim capacitors, consider the trace capacitance and pin capacitance to calculate the crystal loading correctly. Again, the capacitance on each side is in series with the crystal. The total capacitance on both side is twice the specified crystal load capacitance (CL). Trim capacitors are calculated to provide equal capacitive loading on both sides.

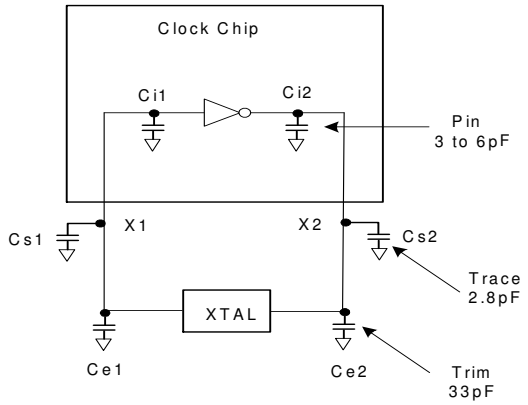


Figure 2. Crystal Loading Example

Use the following formulas to calculate the trim capacitor values for Ce1 and Ce2.

Load Capacitance (each side)

$$Ce = 2 * CL - (Cs + Ci)$$

Total Capacitance (as seen by the crystal)

$$CLe = \frac{1}{\left(\frac{1}{Ce1 + Cs1 + Ci1} + \frac{1}{Ce2 + Cs2 + Ci2}\right)}$$

CL.....Crystal load capacitance

CLe..... Actual loading seen by crystal using standard value trim capacitors

Ce..... External trim capacitors

Cs.....Stray capacitance (terraced)

Ci .....Internal capacitance (lead frame, bond wires, etc.)

Absolute Maximum Conditions

Parameter	Description	Condition	Min.	Max.	Unit
V_{DD}	Core Supply Voltage		–	4.6	V
V_{IN}	Input Voltage	Relative to V_{SS}	–0.5	4.6	V_{DC}
T_S	Temperature, Storage	Non-functional	–65	150	°C
T_A	Temperature, Operating Ambient	Functional	-40	85	°C
T_J	Temperature, Junction	Functional	–	150	°C
$Ø_{JC}$	Dissipation, Junction to Case	Mil-STD-883E Method 1012.1	–	20	°C/W
$Ø_{JA}$	Dissipation, Junction to Ambient	JEDEC (JESD 51)	–	60	°C/W
ESD_{HBM}	ESD Protection (Human Body Model)	MIL-STD-883, Method 3015	2000	–	V
UL-94	Flammability Rating	At 1/8 in.	V–0		
MSL	Moisture Sensitivity Level		1		

DC Electrical Specifications

Parameter	Description	Condition	Min.	Max.	Unit
VDD	3.3V Operating Voltage	3.3 ± 5%	3.135	3.465	V
V_{IH}	3.3V Input High Voltage		2.0	V_{DD} + 0.3	V
V_{IL}	3.3V Input Low Voltage		V_{SS} – 0.3	0.8	V
V_{IHI2C}	Input High Voltage	SDATA, SCLK	2.2	–	V
V_{ILI2C}	Input Low Voltage	SDATA, SCLK	–	1.0	V
I_{IH}	Input High Leakage Current	Except internal pull-down resistors, $0 < V_{IN} < V_{DD}$	–	5	µA
I_{IL}	Input Low Leakage Current	Except internal pull-up resistors, $0 < V_{IN} < V_{DD}$	–5	–	µA
V_{OH}	3.3V Output High Voltage	I_{OH} = –1 mA	2.4	–	V
V_{OL}	3.3V Output Low Voltage	I_{OL} = 1 mA	–	0.4	V
I_{OZ}	High-impedance Output Current		–10	10	µA
C_{IN}	Input Pin Capacitance		1.5	5	pF
C_{OUT}	Output Pin Capacitance			6	pF
L_{IN}	Pin Inductance		–	7	nH
V_{XIH}	Xin High Voltage		$0.7V_{DD}$	V_{DD}	V
V_{XIL}	Xin Low Voltage		0	$0.3V_{DD}$	V
$I_{DD3.3V}$	Dynamic Supply Current		–	40	mA

AC Electrical Specifications

Parameter	Description	Condition	Min.	Max.	Unit
Crystal					
T_{DC}	XIN Duty Cycle	The device operates reliably with input duty cycles up to 30/70 but the REF clock duty cycle will not be within specification	47.5	52.5	%
T_{PERIOD}	XIN Period	When XIN is driven from an external clock source	69.841	71.0	ns
T_R/T_F	XIN Rise and Fall Times	Measured between $0.3V_{DD}$ and $0.7V_{DD}$	–	10.0	ns
T_{CCJ}	XIN Cycle to Cycle Jitter	As an average over 1-µs duration	–	500	ps
SRC					
T_{DC}	SRC Duty Cycle	Measured at 0V differential	45	55	%
T_{PERIOD}	100 MHz SRC Period	Measured at 0V differential @ 0.1s	9.99900	10.0010	ns
$T_{PERIODSS}$	100 MHz SRC Period, SSC	Measured at 0V differential @ 0.1s	10.02406	10.02607	ns
$T_{PERIODAbs}$	100 MHz SRC Absolute Period	Measured at 0V differential @ 1 clock	9.87400	10.1260	ns
$T_{PERIODSSAbs}$	100 MHz SRC Absolute Period, SSC	Measured at 0V differential @ 1 clock	9.87406	10.1762	ns
T_{SKEW}	SRC1 to SRC2	Measured at 0V differential		100	ps
T_{CCJ}	SRC Cycle to Cycle Jitter	Measured at 0V differential	–	50	ps
RMS_{GEN1}	Output PCIe* Gen1 REFCLK phase jitter	BER = 1E-12 (including PLL BW 8 - 16 MHz, ζ = 0.54, Td=10 ns, Ftrk=1.5 MHz)	0	108	ps
RMS_{GEN2}	Output PCIe* Gen2 REFCLK phase jitter	Includes PLL BW 8 - 16 MHz, Jitter Peaking = 3dB, ζ = 0.54, Td=10 ns), Low Band, F < 1.5MHz	0	3.0	ps
RMS_{GEN2}	Output PCIe* Gen2 REFCLK phase jitter	Includes PLL BW 8 - 16 MHz, Jitter Peaking = 3dB, ζ = 0.54, Td=10 ns), Low Band, F < 1.5MHz	0	3.1	ps
RMS_{GEN3}	Output phase jitter impact – PCIe* Gen3	Includes PLL BW 2 - 4 MHz, CDR = 10MHz)	0	1.0	ps
L_{ACC}	SRC Long Term Accuracy	Measured at 0V differential	–	100	ppm
T_R / T_F	SRC Rising/Falling Slew Rate	Measured differentially from ±150 mV	2.5	8	V/ns
T_{RFM}	Rise/Fall Matching	Measured single-endedly from ±75 mV	–	20	%
V_{HIGH}	Voltage High			1.15	V
V_{LOW}	Voltage Low		–0.3	–	V
V_{OX}	Crossing Point Voltage at 0.7V Swing		300	550	mV
$T_{jphasepll}$	Phase Jitter (PLL BW 8-16MHz, 5-16MHz)	RMS value		3.1	pS
ENABLE/DISABLE and SET-UP					
T_{STABLE}	Clock Stabilization from Power-up		–	1.8	ms
T_{SS}	Stopclock Set-up Time		10.0	–	ns

Test and Measurement Set-up

For SRC Signals

This diagram shows the test load configuration for the differential SRC outputs

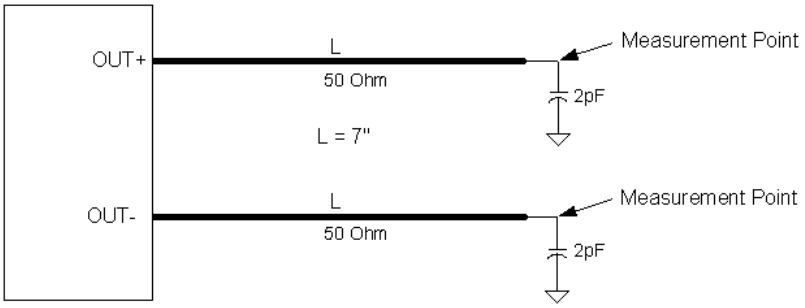


Figure 3. 0.7V Differential Load Configuration

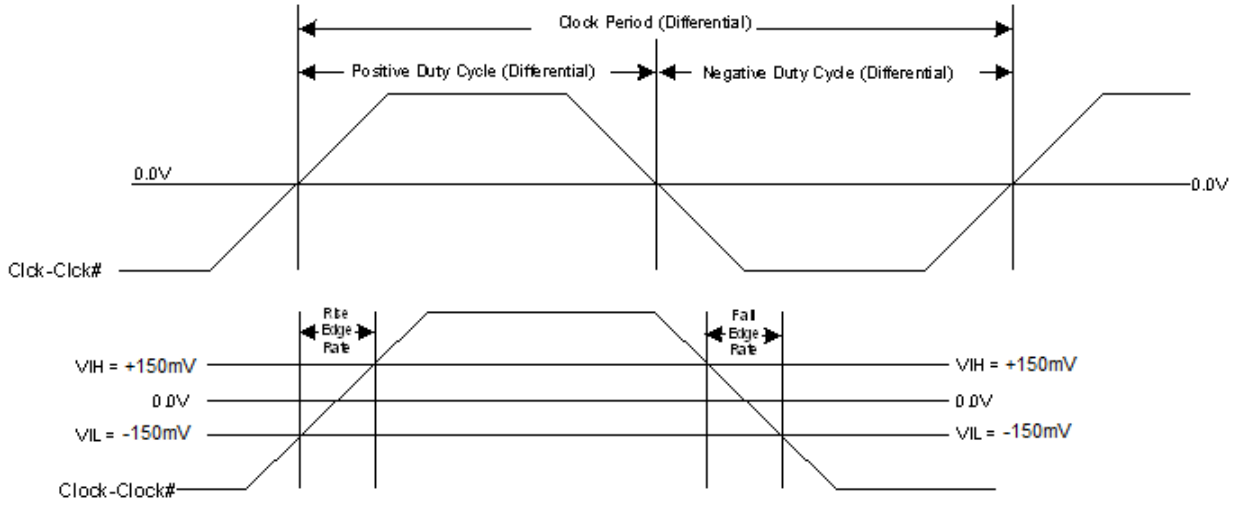


Figure 4. Differential Measurement for Differential Output Signals (for AC Parameters Measurement)

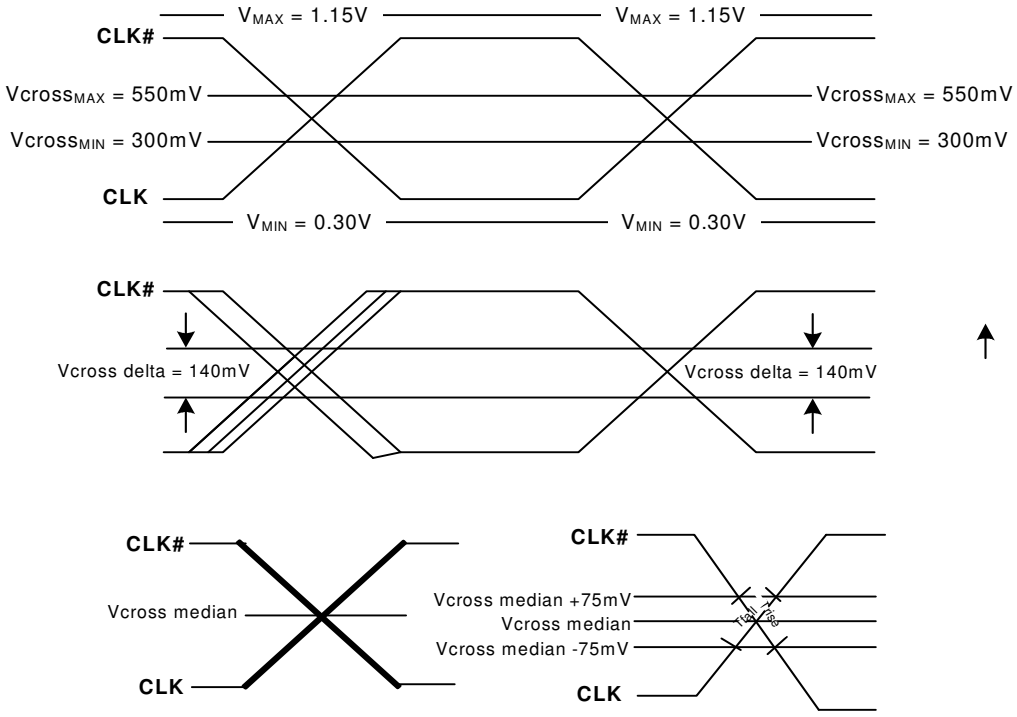
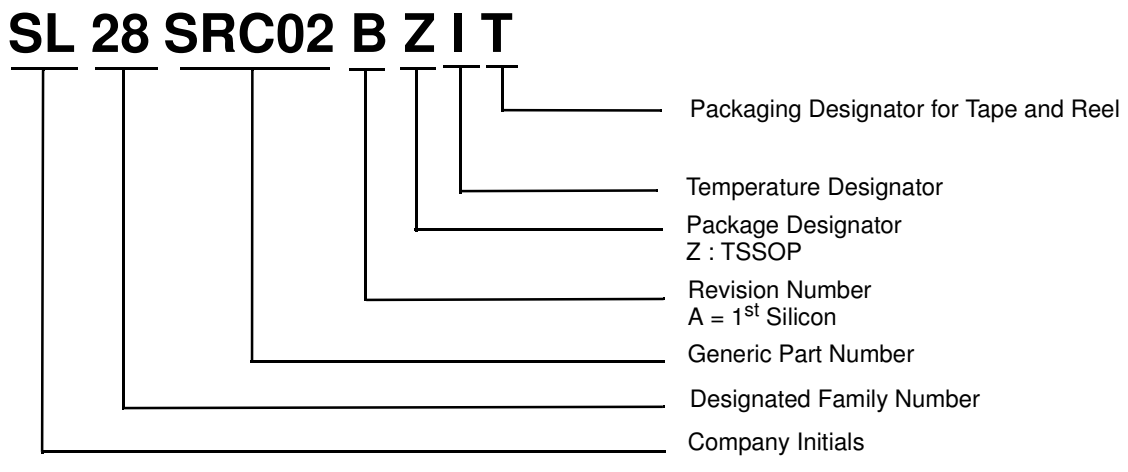


Figure 5. Single-ended Measurement for Differential Output Signals (for AC Parameters Measurement)

Ordering Information

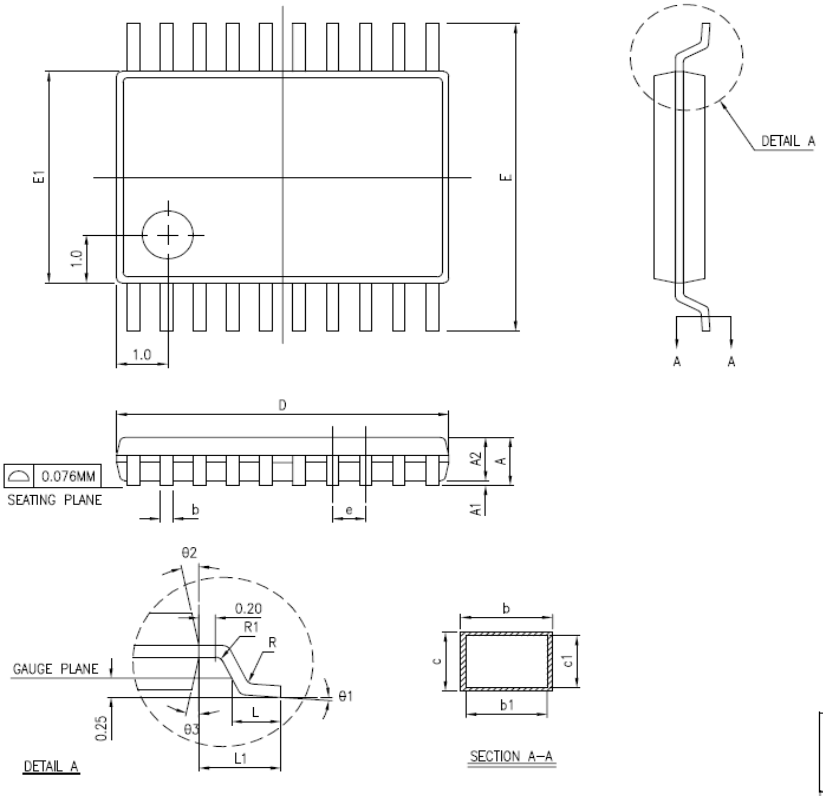
Part Number	Package Type	Product Flow
Lead-free		
SL28SRC02BZI	20-pin TSSOP	Industrial, -40° to 85°C
SL28SRC02BZIT	20-pin TSSOP–Tape and Reel	Industrial, -40° to 85°C



This device is Pb free and RoHS compliant

Package Diagrams

20-pin TSSOP



NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. LEAD COPLANARITY IS 0.003 INCH MAX.

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM	MAX.	MIN.	NOM	MAX.
A			1.20			.043
A1	0.05		0.15	.002		.006
A2	0.80	0.90	1.05	.031	.035	.041
L	0.46	0.61	0.76	.018	.024	.030
D	6.40	6.50	6.60	.252	.256	.260
E	6.30	6.40	6.50	.248	.252	.256
E1	4.30	4.40	4.50	.169	.173	.177
R	0.09			.004		
R1	0.09			.004		
b	0.19		0.30	.007		.012
b1	0.19	0.22	0.25	.007	.009	.010
c	0.09		0.20	.004		.008
c1	0.09		0.16	.004		.006
L1	1.0 REF.			.039 REF.		
e	0.65 BSC.			.026 BSC.		
θ1	0		8	0		8
θ2	12 REF.			12 REF.		
θ3	12 REF.			12 REF.		
N	20					
REF	JEDEC MO-153 VARIATION AC					

SPECTRALINEAR INC.
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SANTA CLARA, CA
95054
TEL: 408-855-0555
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TITLE:
POD for 20LD TSSOP(173 MIL
0.65MM PITCH

Document History Page

Document Title: SL28SRC02 PCI Express Gen 2 & Gen 3 Clock Generator			
REV.	**Issue Date**	**Orig. of Change**	**Description of Change**
1.0	10/28/09	JMA	New Datasheet
1.1	11/06/09	JMA	Updated Figure 4